

What is claimed is:

- Sub a1 →
1. A tape carrier type semiconductor device comprising:  
a flexible substrate on whose surface wiring is formed; and  
a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate, and
  - 5 wherein said flexible substrate includes a first slit having a connector for connecting both sides of the first slit.
  2. The tape carrier type semiconductor device according to claim 1, wherein the first slit includes a plurality of connectors.
  3. The tape carrier type semiconductor device according to claim 2, wherein parts of the slit, which are separated from each other at the connector, are diverged from each other at the connector in a direction perpendicular to the slit.
  4. The tape carrier type semiconductor device according to claim 3, wherein said flexible substrate includes a plurality of first slits.
  5. The tape carrier type semiconductor device according to claim 4, wherein said flexible substrate includes a second slit for folding said tape carrier type semiconductor device.
  - Sub a2 → 6. The tape carrier type semiconductor device according to claim 5, wherein said flexible substrate includes a rib which is formed substantially perpendicular to the plurality of first slits.
  7. The tape carrier type semiconductor device according to claim 6, a portion of said flexible substrate is changed in shape, thereby to form the rib.
  - Sub a3 → 8. The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate includes a rib which is formed substantially perpendicular to the first slit.
  9. The tape carrier type semiconductor device according to claim 8, wherein a portion of said flexible substrate is changed in shape, thereby to form the rib.

*Sub A4* → 10. A tape carrier type semiconductor device comprising:  
 a flexible substrate on whose surface wiring is formed; and  
 a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate, and

5 wherein said flexible substrate includes a slit for folding said flexible substrate and a rib which is formed substantially perpendicular to the slit.

11. The tape carrier type semiconductor device according to claim 10, a portion of said flexible substrate is changed in shape, thereby to form the rib.

*Sub A5* → 12. A method for manufacturing a carrier type semiconductor device, comprising forming a rib for reducing a warp of a flexible film on and in which a driver circuit and a slit are formed, by changing a shape of the flexible film, when the flexible film is cut into a predetermined length.

13. A flexible substrate, which includes a first slit having a connector for connecting both sides of the first slit, and on whose surface wiring having a predetermined pattern is formed.

14. The flexible substrate according to claim 13, wherein the first slit includes a plurality of connectors.

15. The flexible substrate according to claim 14, wherein parts of the slit, which are separated from each other at the connector, are diverged from each other at the connector in a direction perpendicular to the slit.

16. The flexible substrate according to claim 15, further comprising a second slit for folding said flexible substrate.

17. The flexible substrate according to claim 16, further comprising a rib formed substantially perpendicular to the first slit.

18. The flexible substrate according to claim 17, wherein a portion of said flexible substrate is changed in shape, thereby to form the rib.

*Add A6* →